

**IN THE CLAIMS:**

Please cancel claims 1-10 and add new claims 11 and 12 as follows:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Cancelled)
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Cancelled)
10. (Cancelled)

11. (New) A surface mount semiconductor device fabricated by:  
preforming two solid generally C-shaped folded metal frames and each of said frames  
having a top surface for contacting an electrode of a semiconductor device and a bottom  
contact surface for surface mounting said semiconductor device on a motherboard and  
said folded metal frames forming an isolation gap to provide isolation between said  
folded metal frames;

a coating glue and a focusing cup formed of said coating glue and a reflective  
coating on said focusing cup for focusing a light beam, and

wherein said two metal frames serve as electrodes for a diode and wherein said coating glue adheres said focusing cup to said top surfaces of said frames as a unitary structure without covering an area for contacting said electrode.

12. (New) A surface mount semiconductor device comprising:

two solid preformed generally C-shaped folded metal frames and each of said frames having a top surface for contacting an electrode of a semiconductor device and a bottom contact surface for surface mounting said semiconductor device on a motherboard and said folded metal frames forming an isolation gap to provide isolation between said folded metal frames;

a coating glue and a focusing cup formed of said coating glue and a reflective coating on said coating cup for focusing a light beam, and

wherein said two metal frames serve as electrodes for a diode and wherein said coating glue adheres said focusing cup to said top surfaces of said frames as a unitary structure without covering an area for contacting said electrode.